



DEVICE TYPE:				<b>SEMPAC, INC.</b> Open-Pak™ Technologies <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006											
CUSTOMER:			DIE SIZE:												
WIRE TYPE/ SIZE:			NO. OF WIRES:												
THIRD ANGLE PROJECTION	REVISIONS <table border="1"> <thead> <tr> <th>ECN NO.</th> <th>DATE</th> <th>DESCRIPTION</th> <th>APPROVED</th> </tr> </thead> <tbody> <tr> <td>10475</td> <td>10/17/05</td> <td>INITIAL RELEASE</td> <td>D. BENANDO</td> </tr> </tbody> </table>					ECN NO.	DATE	DESCRIPTION	APPROVED	10475	10/17/05	INITIAL RELEASE	D. BENANDO	12 Lead 4mm x 4mm MLP Open-Pak Bonding Diagram	
ECN NO.	DATE	DESCRIPTION	APPROVED												
10475	10/17/05	INITIAL RELEASE	D. BENANDO												
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER DO NOT SCALE DRAWING															
DRAWN BY W. GRIFFITTS		DATE 10/17/05		PACKAGE SIZE: 4.00mm X 4.00mm		SIZE A	PART NO. MLP4X4-12-OP-01	REV 1							
APP BY P. FLASKERUD		DATE 10/17/05		DIE PAD SIZE: 2.300mm x 2.300mm		SCALE 30X	CAD FILE MLP4X4-12-OP-01-B-R1.DWG	SHEET 1 OF 1							